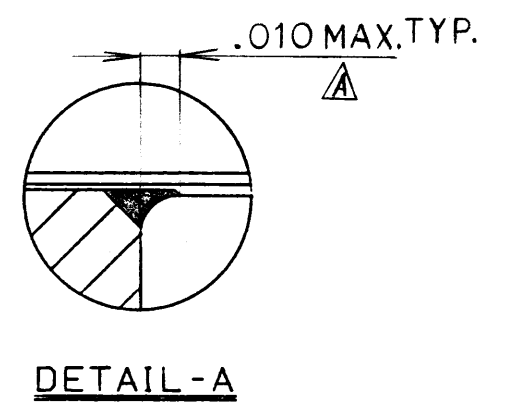
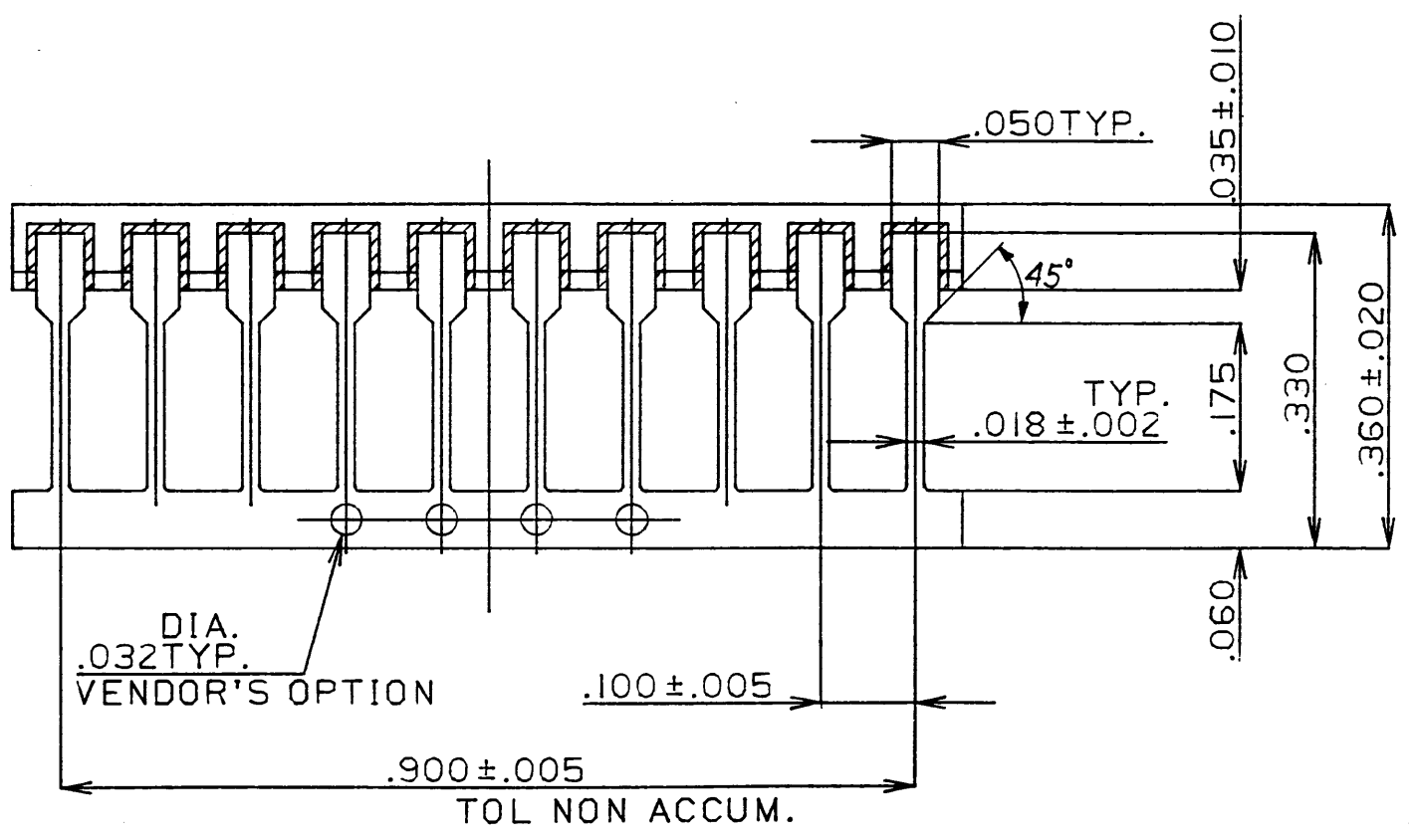
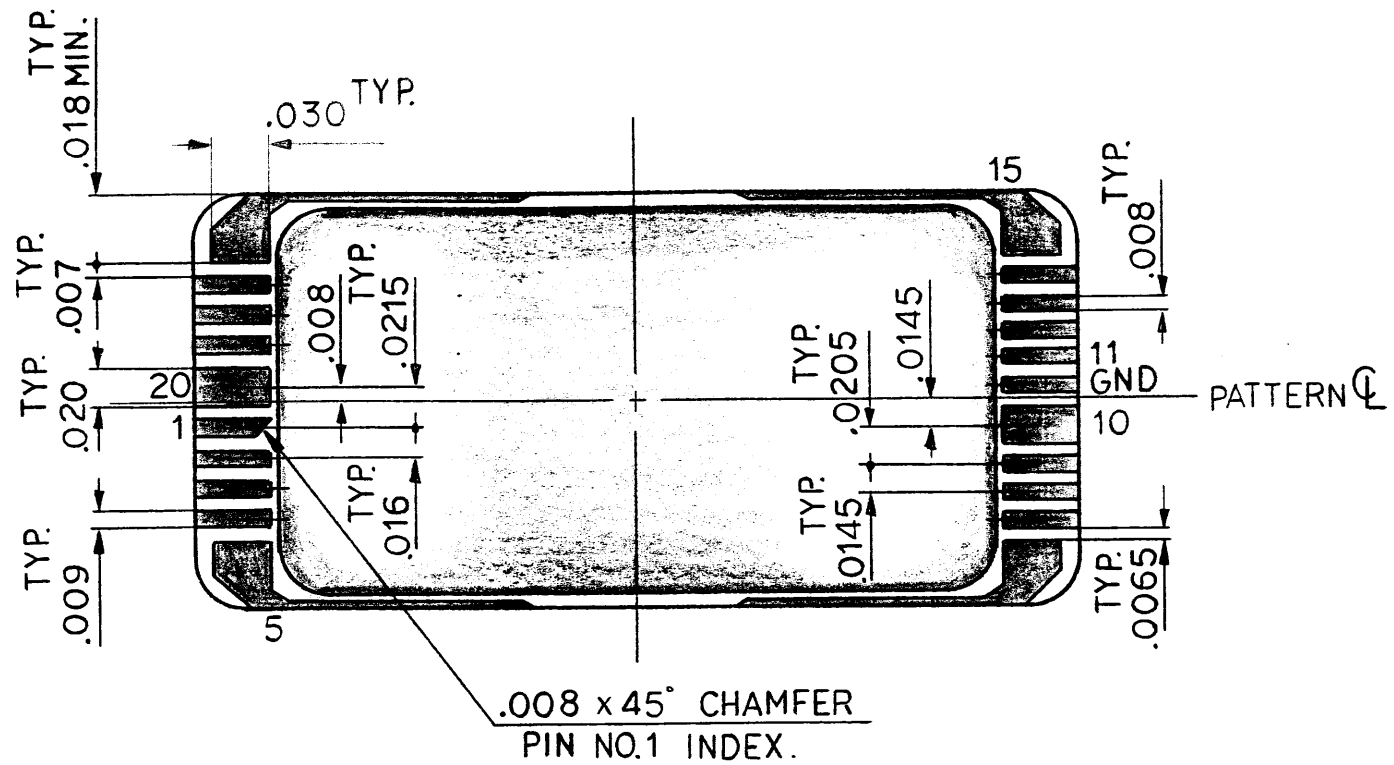


VENDOR'S OPTION



S=0  
 SBO20T735-1 D=0

MODIFICATIONS					NAME 20 LEAD SIDE BRAZED PACKAGE	TOLERANCES: UNLESS OTHERWISE SPECIFIED	DRAWN M. Nishida	CHECKED K. Sakai
					SCALE 5 : 1	MATERIAL AS INDICATED	APPROVED M. Nishida	DATE SEP, 17, '87
						± .005		
	△	ADDED: .010 MAX. TYP.	MAR. 3, '88	H. Yamamoto				
	CHANGE	DATE	DRAWN	CHECKED	APPROVED	KYOCERA CORPORATION KYOTO JAPAN	DWG. NO. KD-S87735-A	1/2



BONDING PATTERN

NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED
3. DIE ATTACH AREA TO BE METALLIZED
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. DIE ATTACH AREA TO BE ELECTRICALLY CONNECTED TO GND PAD.
6. LEAD RESISTANCE : 0.5  $\Omega$  MAX.

MODIFICATIONS						NAME 20 LEAD SIDE BRAZED PACKAGE	TOLERANCES: UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED
						SCALE 10:1		MATERIAL AS INDICATED	<i>[Signature]</i>
								APPROVED	DATE
								<i>[Signature]</i>	SEP. 17, '87
CHANGE	DATE	DRAWN	CHECKED	APPROVED	KYOCERA CORPORATION		KYOTO JAPAN	DWG. NO. KD-S87735-A 2	